

LL4150

List

List..... 1

Package outline..... 2

Features..... 2

Mechanical data..... 2

Maximum ratings and Electrical characteristics2

Rating and characteristic curves..... 3

Pinning information.....4

Marking..... 4

Suggested solder pad layout..... 4

Packing information..... 5

Reel packing..... 6

Suggested thermal profiles for soldering processes..... 6

High reliability test capabilities.....7

LL4150

500mW Surface Mount Switching Diode 50V

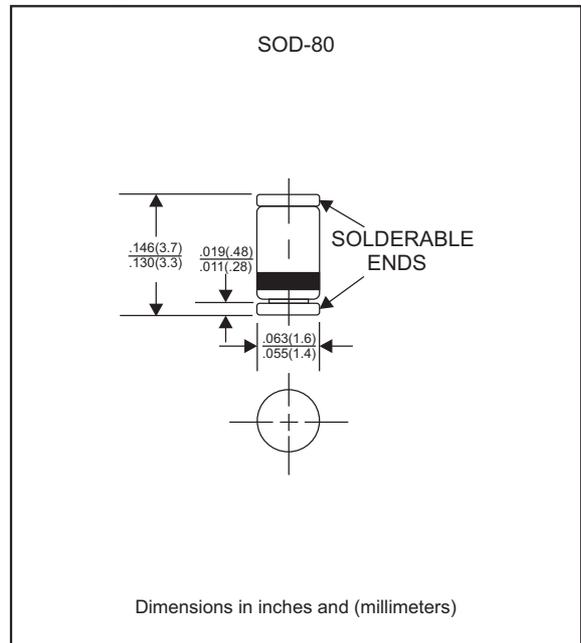
Features

- Fast speed switching.
- Silicon epitaxial planar construction.
- Surface mount package ideally suited for automatic insertion.
- Small surface mounting type.
- Lead-free parts meet RoHS requirements.

Mechanical data

- Case : GLASS MINI-MELF / SOD-80
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.03 gram

Package outline



Maximum ratings and Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Reverse voltage		V_R			50	V
Peak reverse voltage		V_{RM}			50	V
RMS voltage		V_{RMS}			35	V
Average forward current		$I_{F(AV)}$			200	mA
Peak forward surge current	$t_p < 1 \text{ s}$	I_{FSM}			500	mA
Power dissipation	$T_A = 25^\circ\text{C}$	P_D			500	mW
Forward voltage	$I_F = 200 \text{ mA}$	V_F			1.0	V
Reverse current	$V_R = 50 \text{ V}$	I_R			0.1	μA
Diode capacitance	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$	C_T			4.0	pF
Reverse recovery time	$I_F = 10 \text{ mA}$, $V_R = 6 \text{ V}$, $I_{RR} = 1 \text{ mA}$, $R_L = 100\Omega$	t_{rr}			4.0	ns
Typical thermal resistance		$R_{\theta JA}$		350		$^\circ\text{C/W}$
Operating junction temperature range		T_J	-65		+175	$^\circ\text{C}$
Storage temperature range		T_{STG}	-65		+175	$^\circ\text{C}$

Rating and characteristic curves (LL4150)

Fig.1 POWER DERATING CURVE

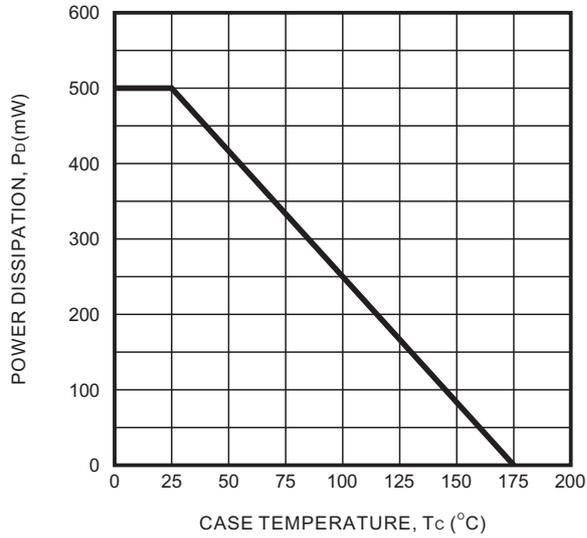


Fig.2 TYPICAL FORWARD CHARACTERISTICS

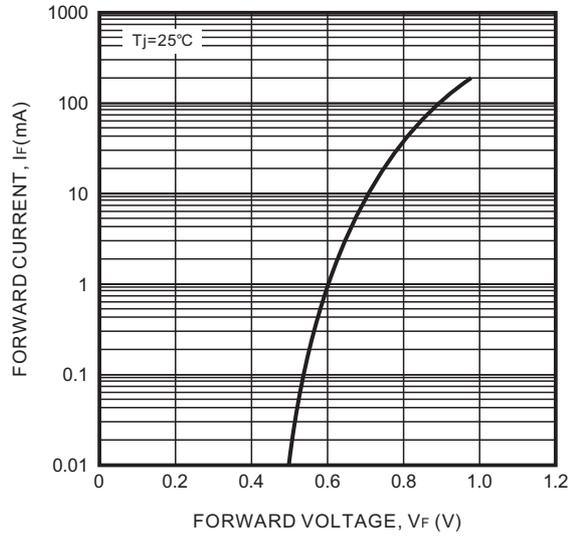


Fig.3 TYPICAL CAPACITANCE

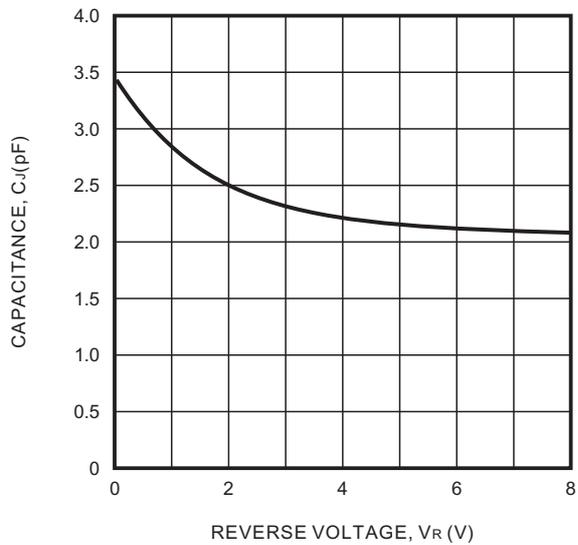
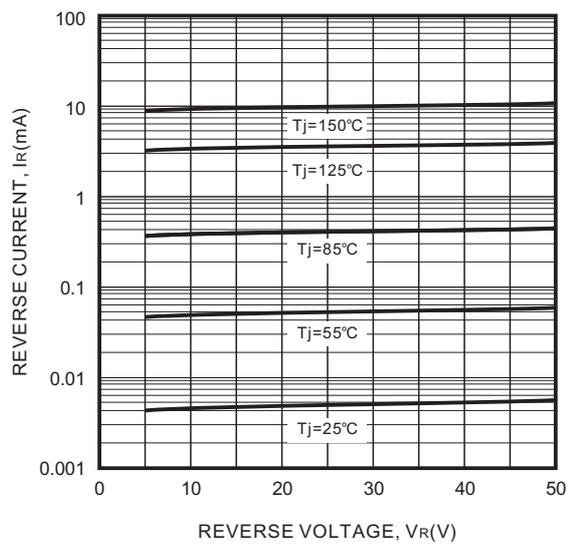


Fig.4 TYPICAL REVERSE CHARACTERISTICS



LL4150

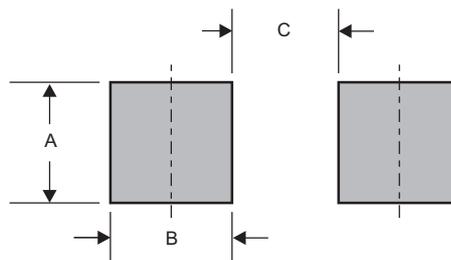
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
LL4150	Cathode band only

Suggested solder pad layout

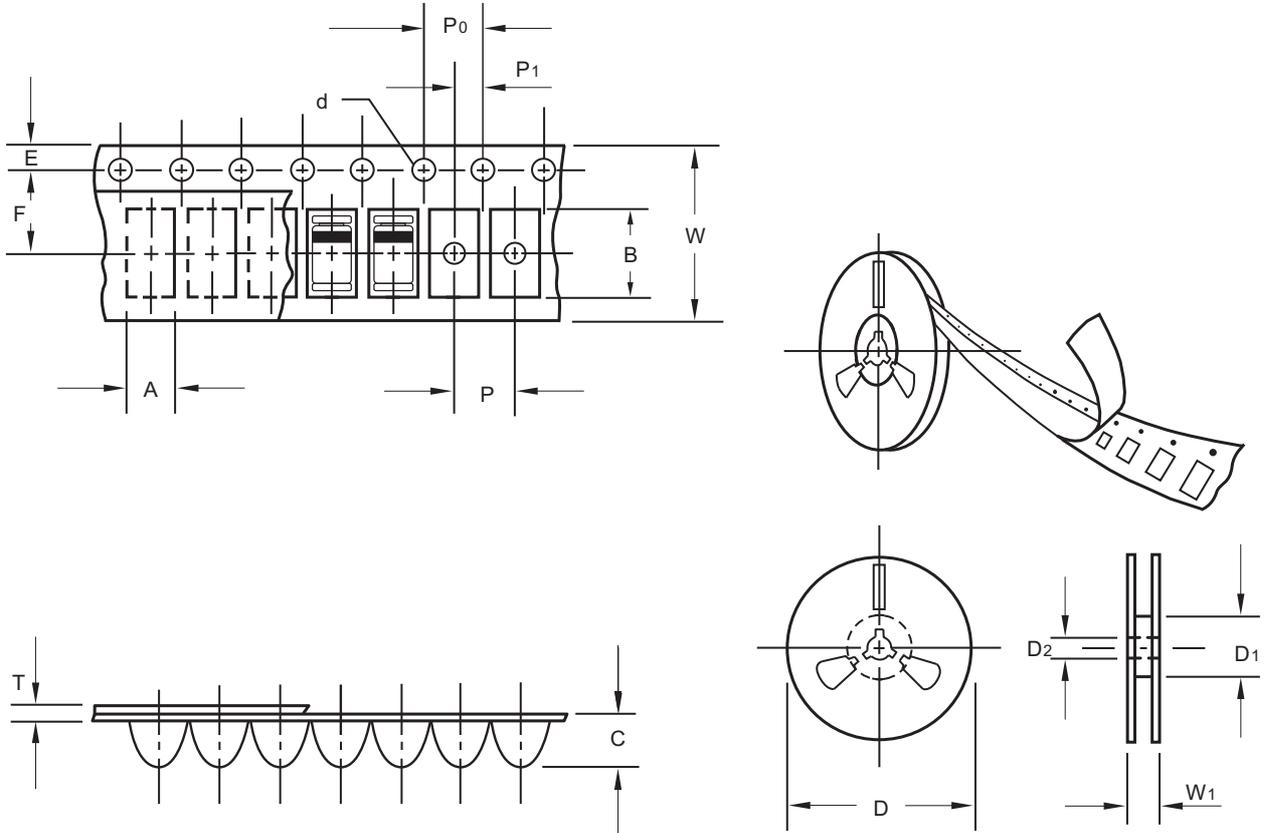


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-80	0.071(1.80)	0.035(0.90)	0.102(2.60)

LL4150

Packing information



unit:mm

Item	Symbol	Tolerance	SOD-80
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.70
Carrier depth	C	0.1	1.80
Sprocket hole	d	0.1	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

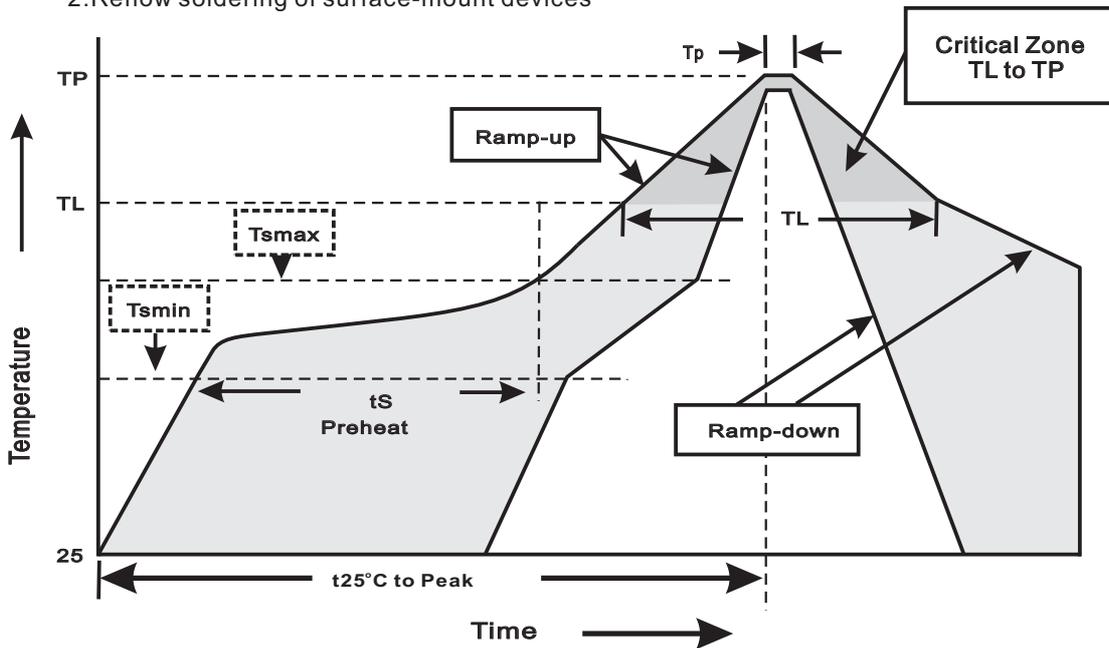
LL4150

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-80	7"	2500	4.0	25,000	183*123*183	178	382*257*387	200,000	9.6

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

LL4150**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=175^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P _{SIG} at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	Peak Forward Current at $t_p = 1 \mu\text{s}$	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031